

ABSTRACT

Disclosed is a method for connecting microcircuits formed in a circuit board, such as a Tape Carrier Package (TCP), a Flexible Printed Circuit (FPC), a Liquid Crystal Display (LCD) or a printed circuit board using an anisotropic conductive adhesive including conductive particles, and the connection structure manufactured by the above method. The method comprises the steps of applying an insulating film layer to a circuit board having circuit patterns, and then bonding them with an anisotropic conduction adhesive. The circuits that should not be connected by conductive particles included in the anisotropic conductive adhesive are prevented from a short-circuit